Product End-of-Life Disassembly Instructions

Product Category: External Options Monitor and Display

Marketing Name / Model
[List multiple models if applicable.]
HP P244y 23.8-inch Display

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm IF BD, Power BD</td>
<td>2</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain. NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>AC power cord, VGA cable</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

HPI instructions for this template are available at EL-MF877-01
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2 SCREW DRIVER(WAHSER HEAD)</td>
<td>#2</td>
</tr>
<tr>
<td>Description #3 SCREW DRIVER(HEX HEAD)</td>
<td></td>
</tr>
<tr>
<td>Description #4 SPANNER</td>
<td>#10</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove cable from Display head
2. Remove Stand Base From Display Head
3. Remove Rear Cover From Display Head
4. Remove Aluminum Foil
5. Remove Bracket Assembly From Display Head
6. Remove Middle Cover From Display Head

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

HPI instructions for this template are available at EL-MF877-01
Safari Cheetah P244/P244y Disassemble Process

Prepare By: Jove Liu
Date : 2018/12/06
1. Remove cable from display head
2. Remove Stand Base From Display Head

2. Push the red point

3. Remove stand base assembly
3. Remove Rear Cover From Display Head

4. Release the six screw from rear cover by cross screwdriver

5. Remove rear cover
4. Remove Aluminum Foil

6. Remove three Aluminum Foil
5. Remove Bracket Assembly From Display Head

7. Release two screws and remove the OSD cable

8. Remove the interface cable and LED cable

9. Remove Bracket Assembly
6. Remove Middle Cover From Display Head

10. Release all the screws by cross screwdriver

11. Remove middle cover
7. Disassemble Bracket Assembly

1. Remove black Mylar
7. Disassemble Bracket Assembly

2. Release the four screws from bracket by cross screwdriver

3. Release the five screws from BD by cross screwdriver

4. Remove interface and power BD
7. Disassemble Bracket Assembly

4. Remove EMI gaskets and white Mylar
8. Disassemble Mid-cover Assembly

1. Remove OSD BD

2. Remove OSD KEY

3. Remove lens
9. Disassemble Rear-cover Assembly

1. Release two screws by cross screwdriver
2. Remove wall mount
10. Disassemble Stand Assembly

20. Push the release button then remove the stand

21. Release the four screws by cross screwdriver

22. Remove hinge from stand

23. Release four screws from hinge by cross screwdriver
10. Disassemble Stand Assembly

24. Release the two screws and nut from hinge by cross screwdriver

25. Remove all part
11. Disassemble Base Assembly

26. Remove the five rubbers

27. Release eleven screws by cross screwdriver

28. Remove the chassis
01. Back side Shielding disassembly

Use cross screwdriver to unlock the two screws
02. Back side Source board disassembly

Lift up the source board that stick by double tape
12. Disassemble Panel Assembly

03. Front side OC disassembly

Note: there will be residual gum on the OC and MF. It is easy to tear off by hand. (as next page)

Use film to separate the OC and MF
12. Disassemble Panel Assembly

Residual gum on OC

Residual gum on MF
12. Disassemble Panel Assembly

4. Front side middle frame disassembly

loose all the hooks by hand
12. Disassemble Panel Assembly

05. Take out 3pcs film

Note: use hand to carry the suspension loop left and right side to take out the film.
06. Take out LGP

Use tape to stick one bottom corner of the LGP, then take it out.

note: use hand to hold the two sides when take out LGP.
07. Take out reflector

Use tape to stick one bottom corner of the reflector plate, then take it out.
12. Disassemble Panel Assembly

08. Take out light bar

Note: Light bar can’t be reused after take out.

Use knife to separate light bar and BC then take out light bar.
Thank You !!!